

Final Product/Process Change Notification Document #: FPCN21560X Issue Date: 13 December 2016

Title of Change:	Adding Advanced Semiconductor Engineering Shanghai as a qualified assembly site for NCP81208 products		
Proposed first ship date:	13 March 2017		
Contact information:	Contact your local ON Semiconductor Sales Office or <david.short@onsemi.com></david.short@onsemi.com>		
Samples:	Contact your local ON Semiconductor Sales Office		
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <david.short@onsemi.com>.</david.short@onsemi.com>		
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <pcn.support@onsemi.com>.</pcn.support@onsemi.com>		
Change Part Identification:	ASE-SH assembled parts will have assembly site designator on the bottom line. Pin 1 logo NCP81208 FAWLYYWW PB-Free Designator Trace Code Legend - Front F: Fab Site A: Assembly Site WL: Wafer Lot Number YY: Year of Production, Last Two Numbers WW: Work Week Number WW: Work W		
Change category:	☐ Wafer Fab Change ☐ Assembly Change ☐ Test Change ☐ Other		
Change Sub-Category(s): □ Datasheet/Product Doc change ☑ Manufacturing Site Change/Addition □ Material Change □ Shipping/Packaging/Marking ☑ Manufacturing Process Change □ Other: □ Other: Sites Affected: ☑ All site(s) □ not applicable □ ON Semiconductor site(s) : ☑ External Foundry/Subcon site(s)		□ Datasheet/Product Doc change □ Shipping/Packaging/Marking □ Other: □ External Foundry/Subcon site(s) Advanced Semiconductor Engineering	
Description and Purpose:			

Adding ASE-SH as another assembly site option for NCP81208. This will help ensure supply chain for all customers.

Package Kit	Description
1LF120000612	Lead Frame - QFN48 6x6 .4 Ag Ring
1EY010000063	Epoxy - HITACHI EN4900
1CW010000002	Wire - EX1 PD COPPER 0.8MIL
1EN020000639	Mold Compound - G631H

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Reliability Data Summary:

NCP81208MNTXG & NCP81218MNTXG

Test	Specification	Condition	Interval	Results
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C	1	-
PC+TC	JESD22-A104	Ta= -65°C to +150°C	500cycs	0/80
PC+uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96hrs	0/80
RSH	JESD22- B106	Ta = 265C, 10 sec	Post RSH	0/30

NCP81206MNTXG - Generic Reliability Data

Test	Specification	Condition	Interval	Results
HTOL	JESD22-A108	Ta=125°C, 100 % max rated Vcc	504hrs	0/240
HTSL	JESD22-A103	Ta= 150°C	1008hrs	0/240
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C	-	-
PC+TC	JESD22-A104	Ta= -65°C to +150°C	500cycs	0/240
PC+HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96hrs	0/240
PC+uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96hrs	0/240
RSH	JESD22- B106	Ta = 265C, 10 sec	Post RSH	0/90

Electrical Characteristic Summary: Electrical characteristics are not impacted.

List of affected Standard Parts:

Part Number	Qualification Vehicle	
NCP81208MNTXG	NCP81208MNTXG	
NCP81208TMNTXG	NCP81218MNTXG	
NCP81208AMNTXG	NCP81206MNTXG	

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